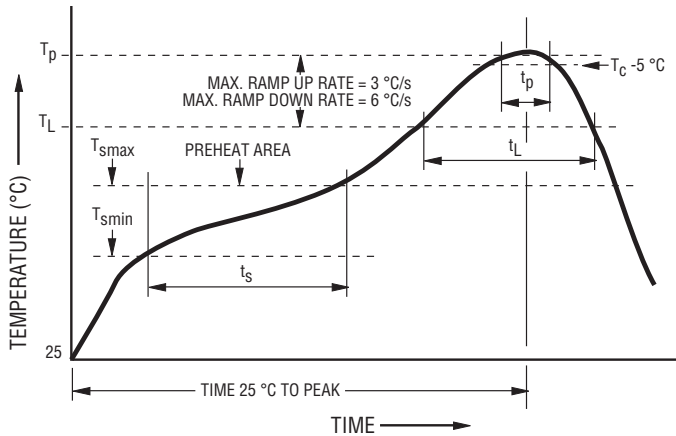


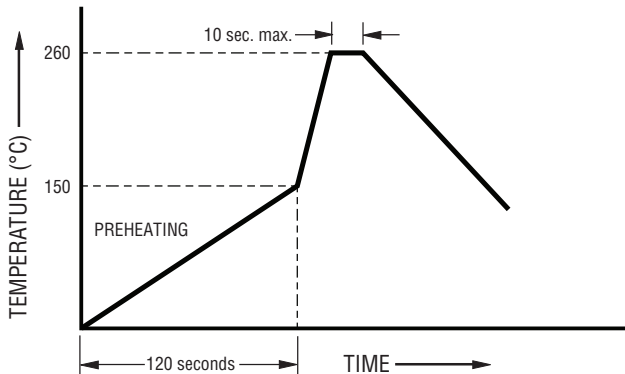
**Solder Reflow Recommendations**



Profile Feature	Pb-Free Assembly
Preheat / Soak: Temperature Min. ( $T_{smin}$ ) Temperature Max. ( $T_{smax}$ ) Time ( $t_s$ ) from ( $T_{smin}$ to $T_{smax}$ )	150 °C 200 °C 60~120 seconds
Ramp Up Rate ( $T_l$ to $T_d$ )	3 °C / second max.
Liquidous Temperature ( $T_l$ ) Time ( $t_L$ ) maintained above $T_l$	217 °C 60~150 seconds
Peak Package Body Temperature ( $T_d$ )	260 °C
Time ( $t_p$ )* within 5 °C of the specified classification temperature ( $T_c$ )	30 seconds*
Ramp Down Rate ( $T_d$ to $T_l$ )	6 °C / second max.
Time 25 °C to Peak Temperature	8 minutes max.

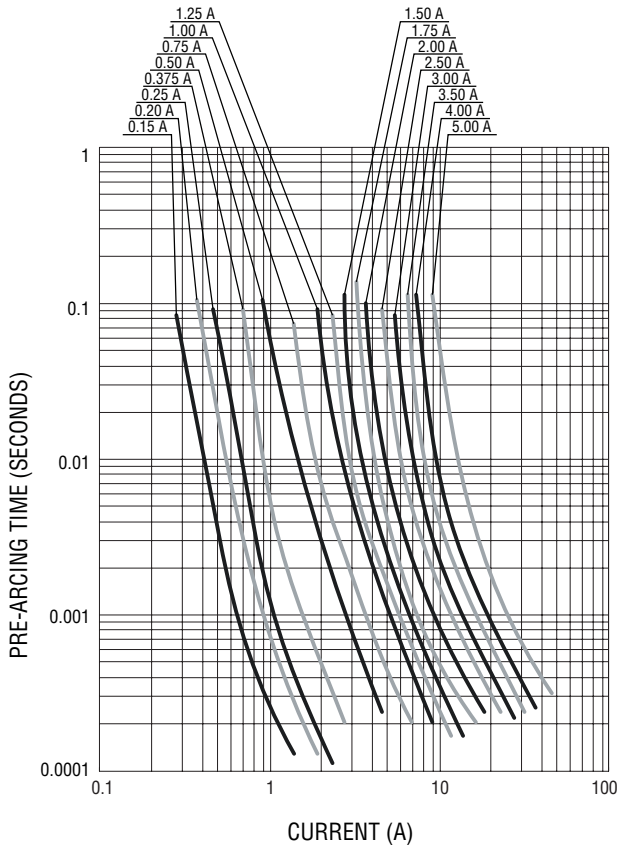
\* Tolerance for peak profile temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.

**Recommended Temperature Profile for Wave Soldering**

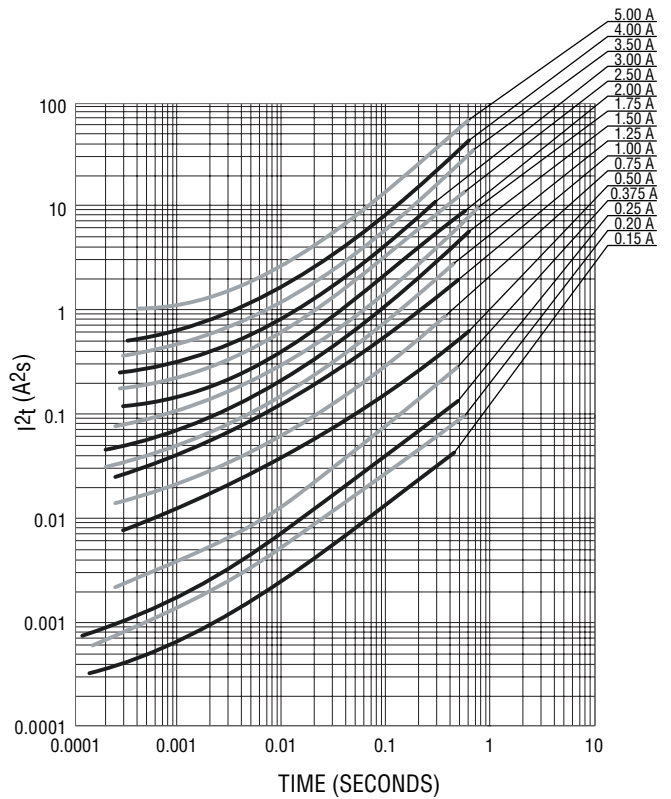


Wave soldering is suitable for 0603 size models.

Average Pre-Arcing Time vs. Current Curves



Average I²t vs. t Curves



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